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July 2014

FDMA1028NZ

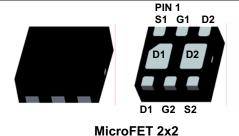
Dual N-Channel PowerTrench® MOSFET

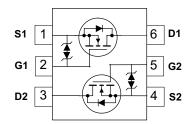
General Description

This device is designed specifically as a single package solution for dual switching requirements in cellular handset and other ultra-portable applications. It features two independent N-Channel MOSFETs with low on-state resistance for minimum conduction losses. The MicroFET 2x2 package offers exceptional thermal performance for its physical size and is well suited to linear mode applications.

Features

- 3.7 A, 20V. $R_{DS(ON)} = 68 \text{ m}\Omega$ @ $V_{GS} = 4.5V$ $R_{DS(ON)} = 86 \text{ m}\Omega$ @ $V_{GS} = 2.5V$
- Low profile 0.8 mm maximum in the new package MicroFET 2x2 mm
- HBM ESD protection level > 2kV (Note 3)
- RoHS Compliant
- Free from halogenated compounds and antimony oxides





Absolute Maximum Ratings T_A=25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V _{DS}	Drain-Source Voltage		20	V
V _{GS}	Gate-Source Voltage		±12	V
1	Drain Current - Continuous	(Note 1a)	3.7	A
I _D	– Pulsed		6	
P _D	Power Dissipation for Single Operation	(Note 1a)	1.4	W
		(Note 1b)	0.7	
T _J , T _{STG}	Operating and Storage Junction Temperature Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	86 (Single Operation)	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1b)	173 (Single Operation)	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1c)	69 (Dual Operation)] *C/vv
R _{eJA}	Thermal Resistance, Junction-to-Ambient	(Note 1d)	151 (Dual Operation)	

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
028	FDMA1028NZ	7"	8mm	3000 units

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
	4	<u> </u>				
	acteristics	T., .,	1 00	1	1	T ,,
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, \qquad I_{D} = 250 \mu\text{A}$	20			V
$\Delta BV_{DSS} \over \Delta T_J$	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, Referenced to 25°C		15		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 16 V, V _{GS} = 0 V			1	μА
I _{GSS}	Gate-Body Leakage	$V_{GS} = \pm 12 \text{ V}, V_{DS} = 0 \text{ V}$			±10	μΑ
On Char	acteristics (Note 2)					
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \ \mu A$	0.6	1.0	1.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	I_D = 250 μ A, Referenced to 25°C		-4		mV/°C
R _{DS(on)}	Static Drain–Source	$V_{GS} = 4.5 \text{ V}, I_{D} = 3.7 \text{ A}$		37	68	mΩ
	On–Resistance	$V_{GS} = 2.5 \text{ V}, I_{D} = 3.3 \text{ A}$		50	86	
		V_{GS} = 4.5 V, I_D = 3.7 A, T_J =125°C		53	90	
g _{FS}	Forward Transconductance	$V_{DS} = 10 \text{ V}, \qquad I_{D} = 3.7 \text{ A}$		16		S
Dynamic	Characteristics					
C_{iss}	Input Capacitance	$V_{DS} = 10 \text{ V}, \qquad V_{GS} = 0 \text{ V},$		340		pF
Coss	Output Capacitance	f = 1.0 MHz		80		pF
C _{rss}	Reverse Transfer Capacitance]		60		pF
Rg	Gate Resistance				25	Ω
Switchin	g Characteristics (Note 2)					
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 10 \text{ V}, \qquad I_{D} = 1 \text{ A},$		8	16	ns
t _r	Turn-On Rise Time	$V_{GS} = 4.5 \text{ V}, R_{GEN} = 6 \Omega$		8	16	ns
$t_{\text{d(off)}}$	Turn-Off Delay Time			14	26	ns
t _f	Turn-Off Fall Time			3	6	ns
Q_g	Total Gate Charge	$V_{DS} = 10 \text{ V}, \qquad I_{D} = 3.7 \text{ A},$		4	6	nC
	Gate-Source Charge	$V_{GS} = 4.5 V$		0.7		nC
Q_{gs}	Gate-Source Charge			0.7		

Electrical Characteristics $T_J = 25$ °C unless otherwise noted

Notes:

- 1. $R_{\theta JA}$ is determined with the device mounted on a 1 in² oz. copper pad on a 1.5 x 1.5 in. board of FR-4 material. $R_{\theta JC}$ is guaranteed by design while $R_{\theta JA}$ is determined by the user's board design.
- user's board design.

 (a) $R_{\theta JA} = 86 \text{ °C/W}$ when mounted on a 1 in² pad of 2 oz copper, 1.5 " x 1.5 " x 0.062 " thick PCB. For single operation.
 - (b) $R_{\theta,IA} = 173$ °C/W when mounted on a minimum pad of 2 oz copper. For single operation.
 - (c) $R_{\theta JA} = 69$ °C/W when mounted on a 1 in² pad of 2 oz copper, 1.5 " x 1.5 " x 0.062 " thick PCB. For dual operation.
 - (d) $R_{\theta JA}$ = 151 °C/W when mounted on a minimum pad of 2 oz copper. For dual operation.



a. 86 °C/W when mounted on a 1 in² pad of 2 oz copper



b. 173 °C/W when mounted on a minimum pad of 2 oz copper



c. 69 °C/W when mounted on a 1 in² pad of 2 oz copper



d. 151 °C/W when mounted on a minimum pad of 2 oz copper

- 2. Pulse Test : Pulse Width < 300 us, Duty Cycle < 2.0%
- 3. The diode connected between the gate and source serves only as protection against ESD. No gate overvoltage rating is implied.

Typical Characteristics

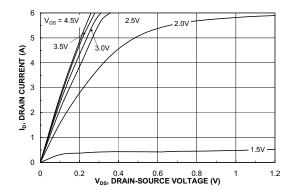
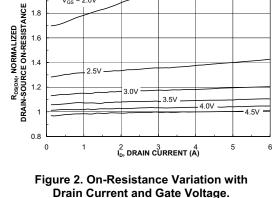


Figure 1. On-Region Characteristics.



 $V_{GS} = 2.0V$

Drain Current and Gate Voltage.

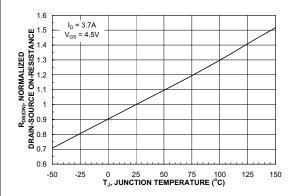


Figure 3. On-Resistance Variation with Temperature.

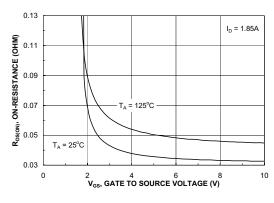


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

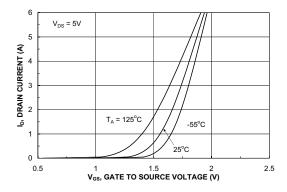


Figure 5. Transfer Characteristics.

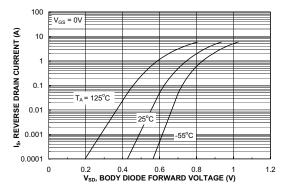
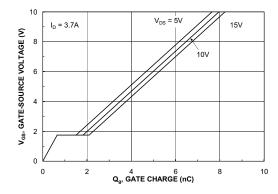


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics

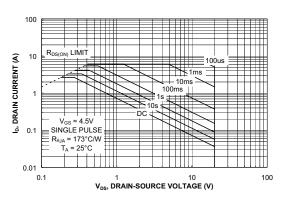


f = 1MHz V_{GS} = 0 V 400 **CAPACITANCE (pF)**000
002 100 $^{5}_{\mathrm{DS}}$, DRAIN TO SOURCE VOLTAGE (V)

500

Figure 7. Gate Charge Characteristics.





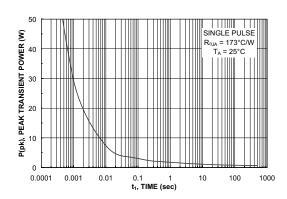


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

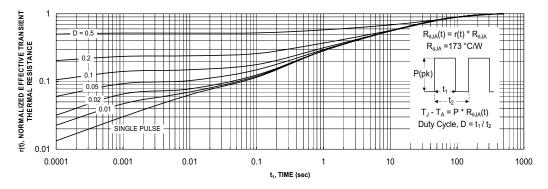
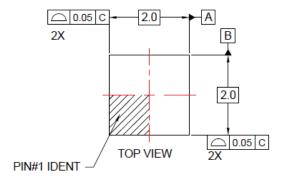
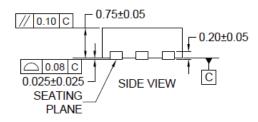


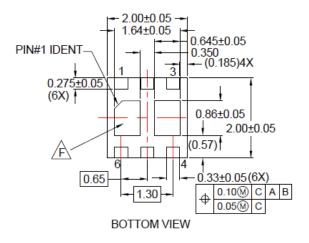
Figure 11. Transient Thermal Response Curve.

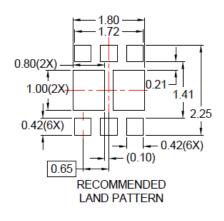
Thermal characterization performed using the conditions described in Note 1b. Transient thermal response will change depending on the circuit board design.

Dimensional Outline and Pad Layout









NOTES:

- A. CONFORM TO JADEC REGISTRATIONS MO-229, VARIATION VCCC, EXCEPT WHERE NOTED.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.
- E. DRAWING FILENAME: MKT-UMLP16Erev4
- F. NON-JEDEC DUAL DAP



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